

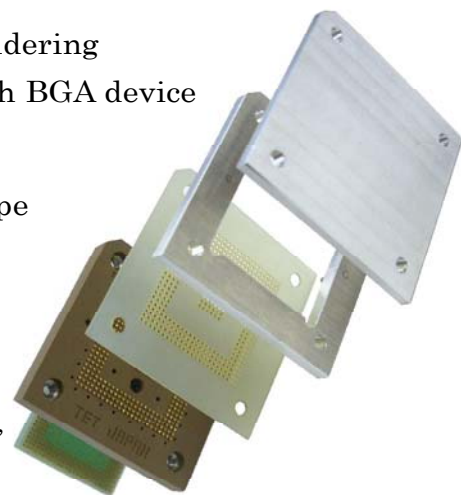
BGA Socket Series

Outline of BGA Socket Series

TET's BGA socket can load BGA device without soldering since socket has pogo pin (movable pin) with which BGA device can keep stable contact.

TET's BGA socket series are for Surface Mount Type and can load BGA, LGA and etc. and also can connect with Emulator Cable or Adapter Board.

TET is ready to develop BGA sockets for custom packages requiring particular pin number, pitch and etc.



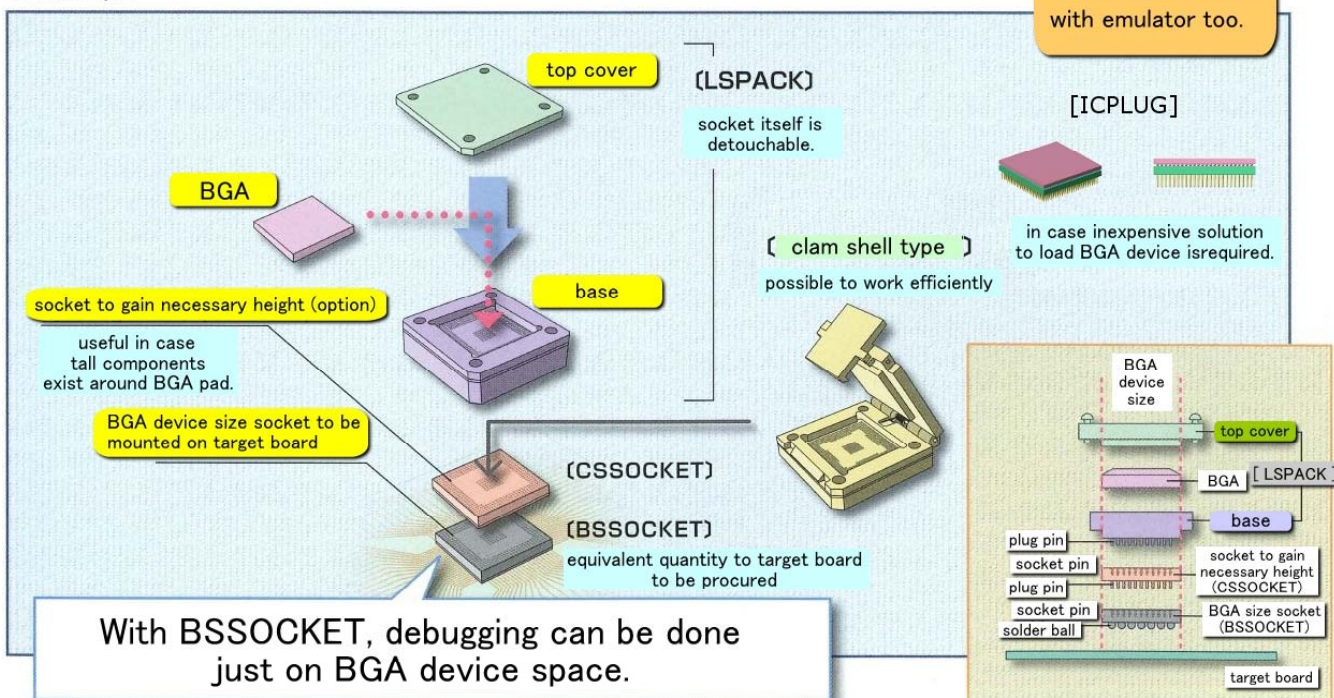
LSPACK

LSPACK can load BGA device in combination with BGA size socket



- Using BSSOCKET in combination with CSSOCKET having same size as BGA device, necessary height can be gained and even tall components can be placed around BGA pad.
- complying with demand of narrow pitch up to 0.4mm.
- As a low cost solution, TET's ICPLUG loading BGA device can be also chosen because ICPLUG is directly mated with BSSOCKET without using LSPACK.

● Example

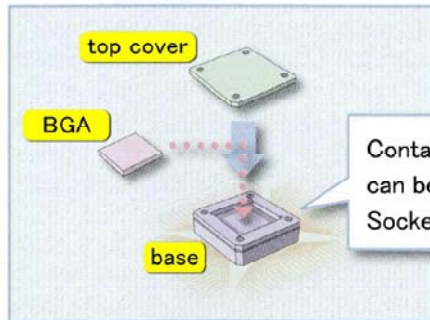


DSPACK

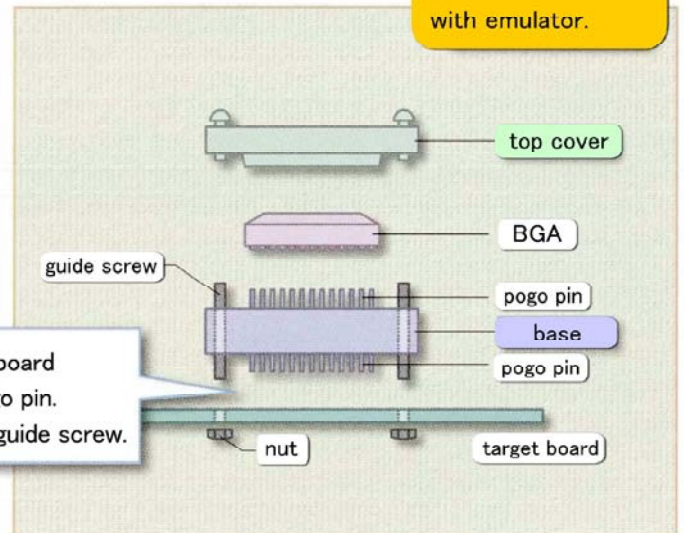


DSPACK doesn't need soldering since pogo pins are prepared

DSPACK has pogo pin on Target Board side too and doesn't need to be soldered on board.

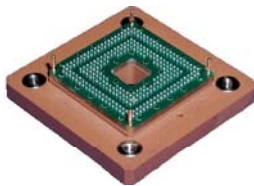


● Example



※Target board must have screw holes for fixing.

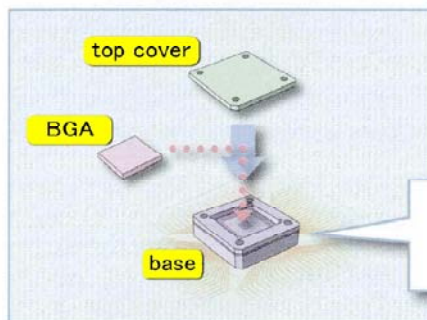
CSPACK



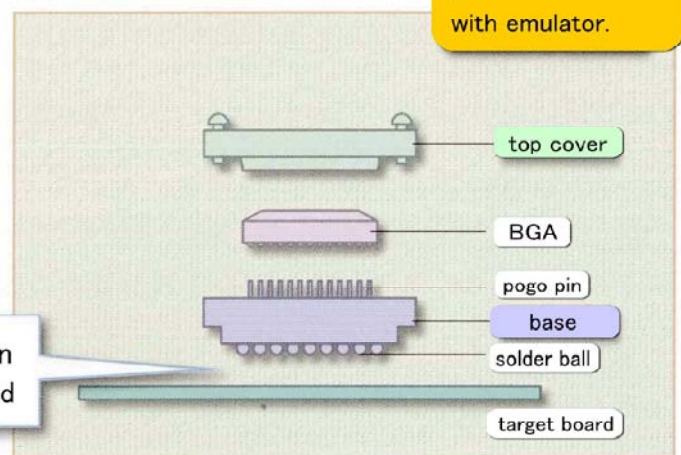
CSPACK is BGA socket with solder ball

As CSPACK has solder balls on the identical position with BGA device foot pattern, reflow soldering can be done.

CSPACK solution is lower cost than combination of LSPACK and BSSOCKET.



● Example



- ※ complying with pin pitch up to 0.65mm (not adaptable to narrower pitch)
- ※ CSPACK is not recommendable for more than 1000 pins as temperature will not be equally distributed to all pins and sufficient soldering can not be expected.

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